# TEMIC

### VHF/ UHF-Tuner-IC

### **Description**

This tuner IC requires a power supply of 12 V and performs the function of three separate oscillators and

mixers, SAWF-driver, L.O.-output and tri-state band switch. Applications are 12 V TV- and VCR-tuners.

#### **Features**

- Frequency range from 48 to 860 MHz
- Band A: balanced high impedance mixer input and amplitude controlled oscillator
- Band B + C: balanced low impedance mixer input and symmetrical oscillator
- Balanced L.O.-output for prescalers or PLL
- SAW filter driver with low impedance output

- Voltage regulator for stable operating characteristics
- ESD protection on all pins except oscillator pins and RF-inputs

### **Benefits**

• The integration of 3 bands allows to design economical 3-band tuners

### **Block Diagram**

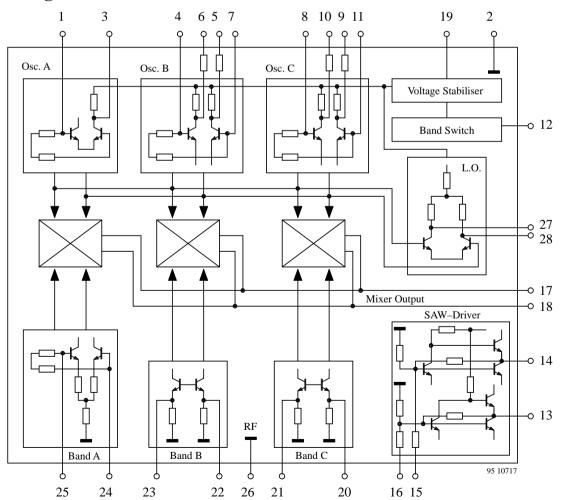


Figure 1. Block diagram

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# **U2300B**

**TELEFUNKEN Semiconductors** 

## **Pin Description**

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Osc A, base	1	28	L.O. out
GND (common)	2	27	L.O. out
Osc A, coll.	3	26	GND (RF)
Osc B, base	4	25	RF in, A
Osc B, coll.	5	24	RF in, A
Osc B, coll.	6	23	RF in, B
Osc B, base	7	22	RF in, B
Osc C, base	8	21	RF in, C
Osc C, coll.	9	20	RF in, C
Osc C, coll.	10	19	$V_S$
Osc C, base	11	18	Mix out
Band sw.	12	17	Mix out
SAWF, out	13	16	SAWF, inp.
SAWF, out	14	15	SAWF, inp.
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Pin	Symbol	Function
1	Osc A, base	Oscillator band A, base
2	GND (common)	Ground, common
3	Osc A, coll.	Oscillator band A, collector
4, 7	Osc B, base	Oscillator band B, bases
5, 6	Osc B, coll.	Oscillator band B, collectors
8, 11	Osc C, base	Oscillator band C, bases
9, 10	Osc C, coll.	Oscillator band C, collectors
12	Band sw.	Tri-state band switch
13, 14	SAWF, out	SAW filter driver outputs
15, 16	SAWF, inp.	SAW filter driver inputs
17, 18	Mix out	Mixer outputs, open collector
19	Vs	Supply voltage V <sub>s</sub>
20, 21	RF in, C	RF inputs, band C
22, 23	RF in, B	RF inputs, band B
24, 25	RF in, A	RF inputs, band A
26	GND (RF)	Ground, RF part
27, 28	L.O. out	L.Ooutputs

# **Ordering Information**

Extended Type Number	Package	Remarks
U2300B-FLG3	SO28	Taped and reeled

# **Absolute Maximum Ratings**

All voltages are referred to GND, Pin 2

Parameters		Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pin 19	$V_{s}$			13.5	V
RF inputs	Pin 20-25				5.0	V
IF outputs	Pin 17-18				13.5	V
Tri-state switch voltage	Pin 12	ViDSW			13.5	V
Junction temperature		$T_{jmax}$			125	°C
Storage temperature		$T_{stg}$	-40		125	°C

### **TELEFUNKEN Semiconductors**

## **Operating Range**

All voltages are referred to GND, Pin 2

Parameters	Test Conditions / Pins	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pin 17-19	$V_{s}$	10.8	12	13.2	V
Ambient temperature		T <sub>amb</sub>	-25		75	°C
Thermal resistance	Test conditions page 5, Package SO-28	R <sub>thJA</sub>		70		K/W

### **Electrical Characteristics**

Test conditions:  $V_s$  = 12 V,  $T_{amb}$  = 25°C, unless otherwise specified, reference point Pin 2, referred to test circuit page 5

			I				
Parameters	Test Condition		Symbol	Min.	Тур.	Max.	Unit
Supply voltage	Pin 17-19		$V_{S}$	10.8	12.0	13.2	V
Supply current	Pin 17-19		$I_S$		42	50	mA
Band switch							
Voltage Band A	Pi	n 12	VSWA	0	0	1.0	V
Voltage Band B	Pi	n 12	VSWB	1.6	2.0	2.4	V
Voltage Band C	Pin	n 12	VSWC	3.4	4.0	5.0	V
Switching current	VSW = 5 V Pin	n 12	ISW			100	μΑ
L.Ooutput							
L.O. level each output	$R_L = 50 \text{ Ohm Pi}$	n 27, 28	PLO	-25		-17	dBm
<b>SAW filter driver</b> fi = 36 M	Hz						
Input impedance	Pi	n 15, 16	ZiSAW		450		Ohm
Output impedance	Pin	n 13, 14	ZoSAW		70		Ohm
Voltage gain	$15, 16 \rightarrow 13$	, 14	GvSAW		18		dB
Band A							
Input frequency range	Pi	n 24	fiA	48		170	MHz
Input impedance	Figure 3	Pin 24	S11A				
Gain (note 4)	Pin I	P to O/P	GA		29		dB
Noise figure DSB (note 2)	Pin I/P to O/P fiA = 50 MHz						
			NF		11.5		dB
	fiA = 150  MHz		NF		12		dB
Input level for (note 3):	Each carrier						
IM3 (interm. of 3rd order	fiA = 71 MHz	Pin I/P	ViA		-21		dBm
IM2 (interm. of 2nd order)	fiA = 71  MHz	Pin I/P	ViA		-21		dBm
Band B (note 1)				1	1		•
Input frequency range	Pin 22, 23		fiB	170		470	MHz
Input impedance	Figure 3 Pin 22, 23		S11B				
Gain (note 4)	Pin I/P to O/P		GB		33		dB
Noise figure DSB (note 2)	Pin I/P to O/P						
	fiB = 200 MHZ		NF		9.5		dB
	fiB = 450  MHz		NF		10		dB
Input level for (note 3)	Each carrier						
IM3 (interm. of 3rd order)	fiB = 300  MHz	Pin I/P	ViB		-26		dBm

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### **TELEFUNKEN Semiconductors**

Parameters	Test Conditions / Pins		Symbol	Min.	Тур.	Max.	Unit
Band C (note 1)							
Input frequency range	Pin 20, 21		fiC	470		860	MHz
Input impedance	Figure 3 Pi	n 20, 21	S11C				
Gain	Pin I/P to O/P		GC		33		dB
Noise figure DSB (note 2)	Pin I/P to O/P						
	fiC = 500 MHZ		NF		10.5		dB
	fiC = 800 MHz		NF		11.5		dB
Input level for (note 3):	Each carrier						
IM3 (interm. of 3rd order)	fiC = 600  MHz	Pin I/P	ViC		-26		dBm

#### Notes

- The RF input B and C are symmetrical driven by means of a hybrid for  $180^{\circ}$  phase shifting, consequently the source impedance is  $100 \Omega$ . All other impedance for RF tests is  $50 \Omega$ .
- The noise figure (NF) is the value for double-side-band measurement.
- The intermodulation test (2-carrier-method) which is made on IF-centre is in reference to a signal-to-IM ratio of 60 dB.
- Gain is the ratio of the voltage at the primary coil of L5 to the available voltage at the input.

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### **Test and Principle Application Circuit**

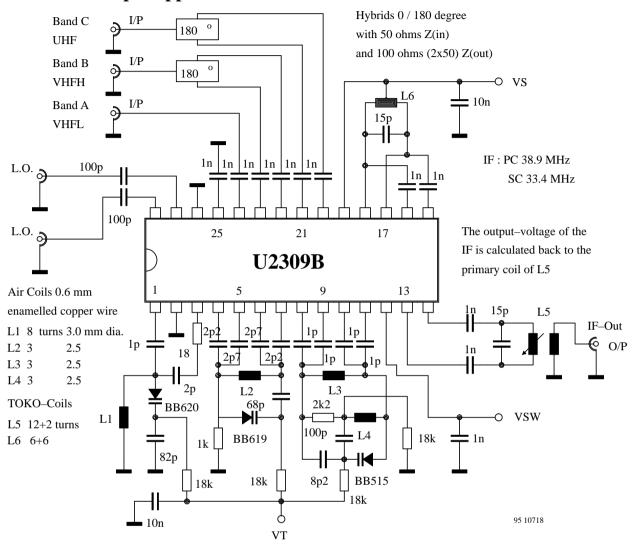


Figure 1. Test and principle application circuit

### PCB for the R<sub>thJA</sub>-Measurement

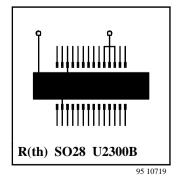
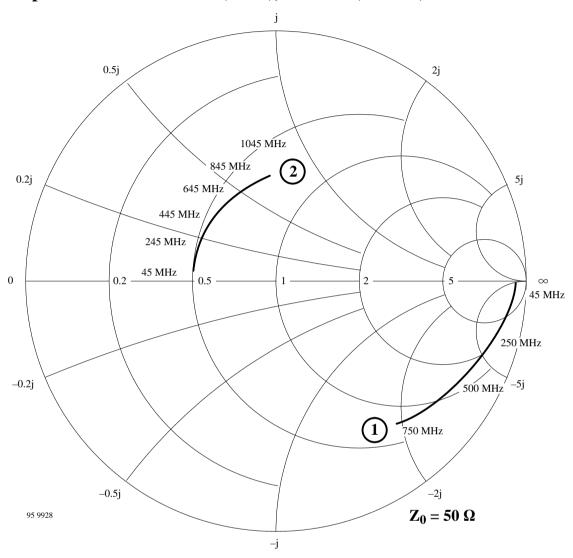


Figure 2. PCB for the  $R_{thJA}$ -Measurement

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### Input Impedance Mixer Band A (S11A), B and C (S11B/C)



#### 1 VHF-Low

Normalised to 50  $\Omega$ , measuring range 45 MHz to 750 MHz.

#### 2 UHF-High and UHF

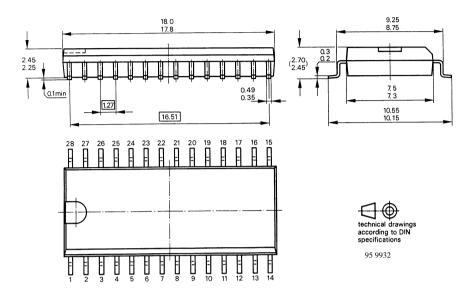
Normalised to 50  $\Omega$ , measuring range 45 MHz to 1045 MHz. Both inputs are driven symmetrical. The output impedance of hybrid is 100  $\Omega$ , the measured levels are then calculated in reference to 50  $\Omega$ .

Figure 3. Input impedance mixer band A (S11A), B and C (S11B/C)

### **TELEFUNKEN Semiconductors**

### **Dimensions in mm**

Package: SO28



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**TELEFUNKEN Semiconductors** 

### **Ozone Depleting Substances Policy Statement**

It is the policy of TEMIC TELEFUNKEN microelectronic GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

**TEMIC TELEFUNKEN microelectronic GmbH** semiconductor division has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

**TEMIC** can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice. Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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